



GE Energy

Functional Testing Specification

*Parts & Repair Operations
Louisville, KY*

LOU-GEF-IC600xx830

Test Procedure for a Series Six Advanced I/O Receiver card

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1. SCOPE

1.1 This is a functional testing procedure for a Series Six Advanced I/O Receiver Card.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.

3.1.1

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to the local documented procedures for cleaning guidelines.

4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires: broken, cracked, or loosely connected

4.2.1.2 Terminal strips / connectors: broken or cracked

4.2.1.3 Components: visually damaged

4.2.1.4 Capacitors: bloated or leaking

4.2.1.5 Solder joints: damaged or cold

4.2.1.6 Circuit board: burned or de-laminated

4.2.1.7 Printed wire runs / Traces: burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		CPU-2 <u>LOCAL</u> RACK

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6. **SETUP**

6.1 Ensure that any jumper settings on the customer card match the settings of the shop card.

7. **TEST PROCESS**

- 7.1 Turn off the power to the CPU-2 LOCAL rack.
- 7.2 The I/O Receiver Card occupies slot 1. Disconnect the top data cable from the top port of the shop I/O Receiver Card.
- 7.3 Disconnect the bottom data cable from the bottom port of the card.
- 7.4 Extract the shop card from slot 1.
- 7.5 Insert the customer card into slot 1.
- 7.6 Connect the top data cable to the top port of the card.
- 7.7 Connect the bottom data cable to the bottom port of the card.
- 7.8 Turn on the power to CPU-2 LOCAL rack.
- 7.9 Ensure that the I/O indicator lights of the other cards within the CPU-2 LOCAL rack light in a downward scrolling pattern.
- 7.10 Allow the rack to run for at least one half hour.
- 7.11 Turn off the power to the CPU-2 LOCAL rack.
- 7.12 Disconnect the top data cable from the top port of the card.
- 7.13 Disconnect the bottom data cable from the bottom port of the card.
- 7.14 Extract the customer card from slot 1.
- 7.15 Insert the shop card back into slot 1.
- 7.16 Connect the top data cable back to the top port of the shop card.
- 7.17 Connect the bottom data cable back to the bottom port of the shop card.
- 7.18 Turn on the power to CPU-2 LOCAL rack.

8. **NOTES**

9. **ATTACHMENTS**